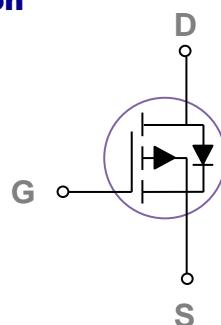
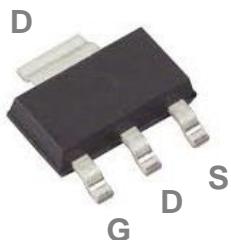


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT223 Pin Configuration



BVDSS	RDS(ON)	ID
-60V	105mΩ	-3.2A

### Features

- -60V, -3.2A, RDS(ON) = 105mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>Ds</sub>	Drain-Source Voltage	-60	V
V <sub>Gs</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous ( $T_A=25^\circ\text{C}$ )	-3.2	A
	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	-5	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup> ( $T_A=25^\circ\text{C}$ )	-12.8	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	25	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	-18	A
P <sub>D</sub>	Power Dissipation ( $T_A=25^\circ\text{C}$ )	2	W
	Power Dissipation ( $T_c=25^\circ\text{C}$ )	5.4	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	23	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$ , $I_D=-1\text{mA}$	---	-0.05	---	$\text{V}/\text{ }^{\circ}\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-60\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{DS}=-48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125\text{ }^{\circ}\text{C}$	---	---	-10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$ , $I_D=-3\text{A}$	---	87	105	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-2\text{A}$	---	107	140	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
			---	3	---	$\text{mV}/\text{ }^{\circ}\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=-10\text{V}$ , $I_D=-3\text{A}$	---	5.5	---	S

**Dynamic and switching Characteristics**

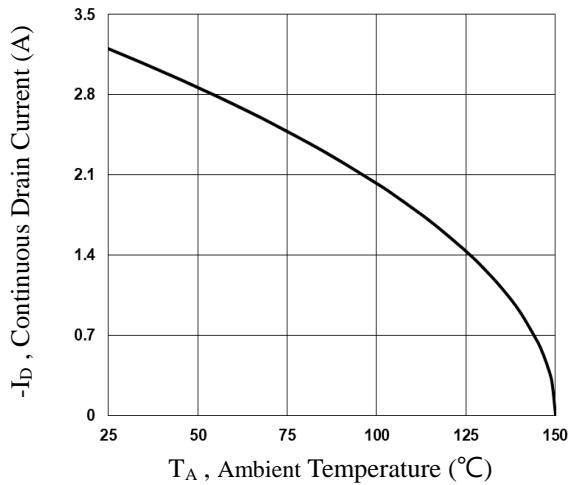
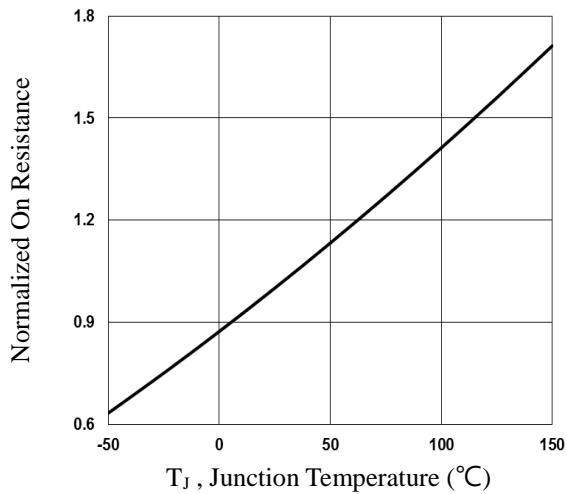
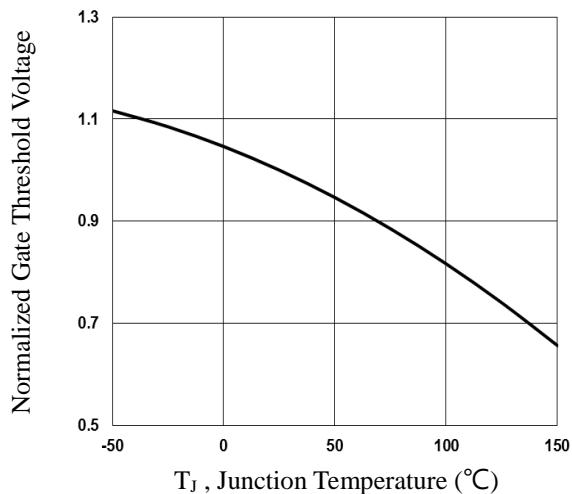
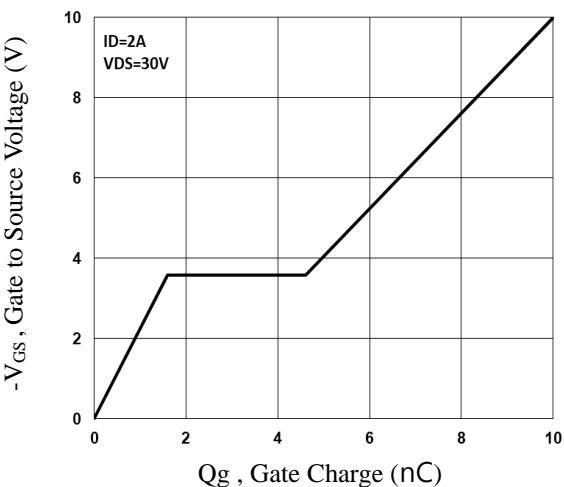
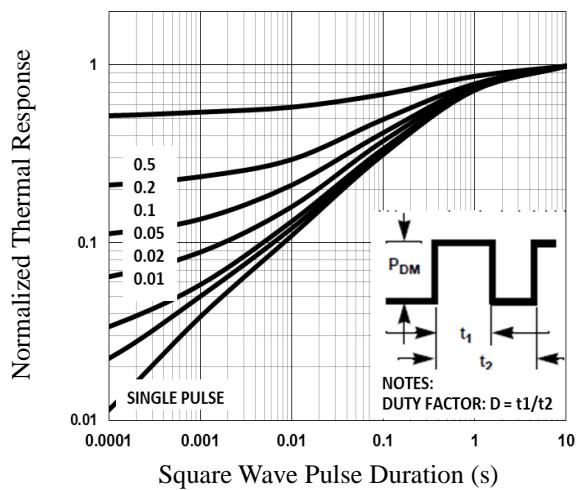
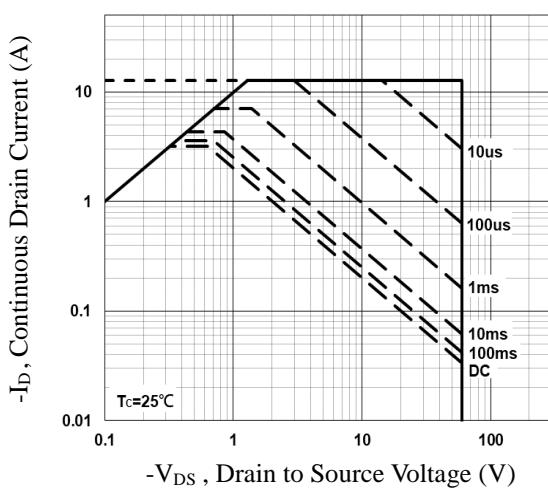
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=-30\text{V}$ , $V_{GS}=-10\text{V}$ , $I_D=-2\text{A}$	---	10	15	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	1.6	3.2	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	3	6	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=-30\text{V}$ , $V_{GS}=-10\text{V}$ , $R_G=6\Omega$	---	8	16	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	15.4	30	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	42.8	80	
$T_f$	Fall Time <sup>3, 4</sup>		---	8.4	16	
$C_{iss}$	Input Capacitance	$V_{DS}=-30\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	785	1300	pF
$C_{oss}$	Output Capacitance		---	175	300	
$C_{rss}$	Reverse Transfer Capacitance		---	112	220	
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	36	---	$\Omega$

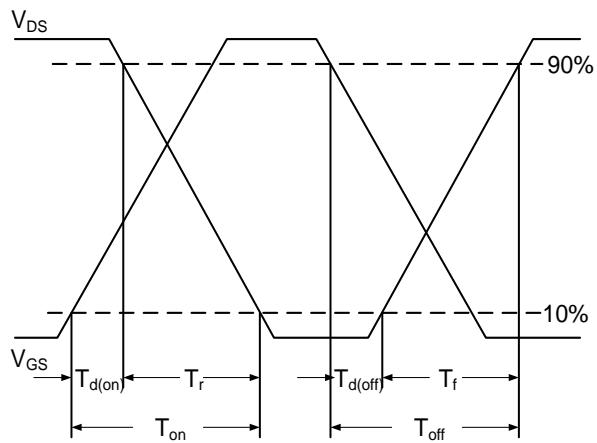
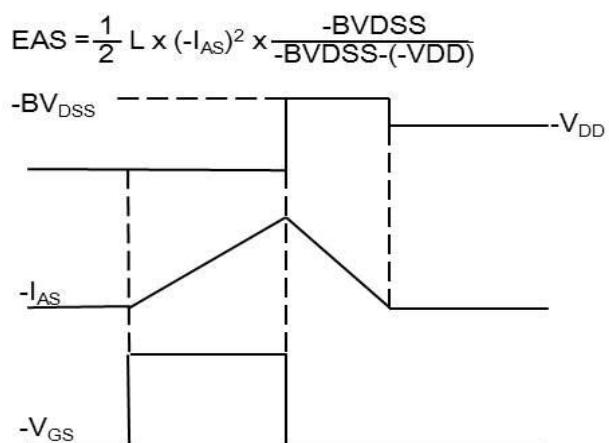
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-3.2	A
			---	---	-6.4	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V

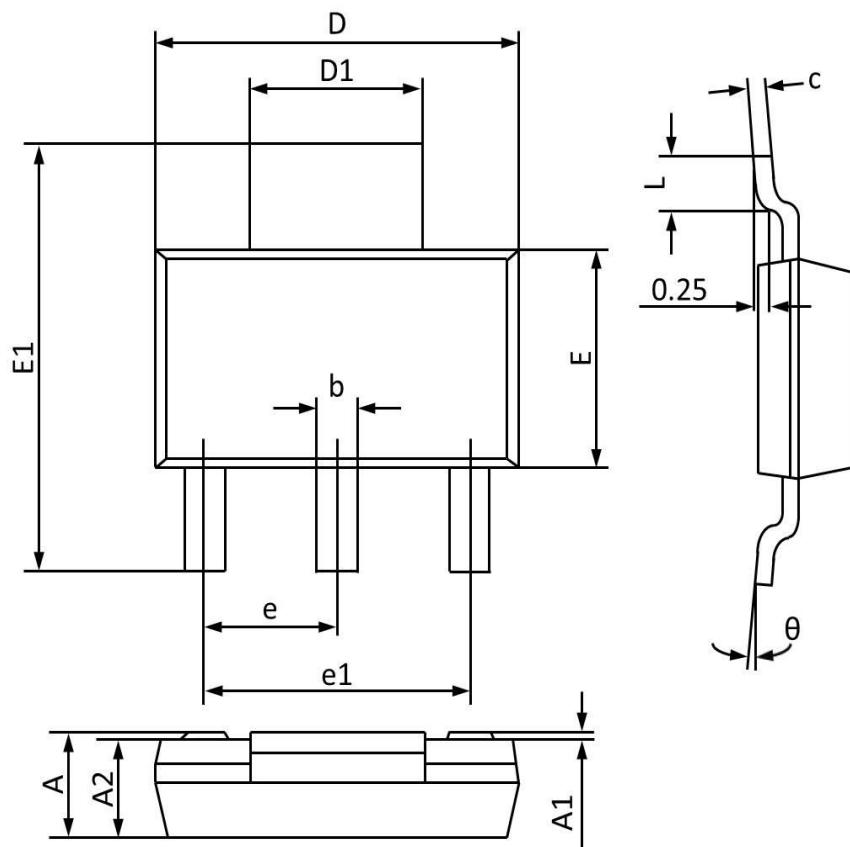
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-25\text{V}$ ,  $V_{GS}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=-18\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. TA**

**Fig.2 Normalized RDSON vs. TJ**

**Fig.3 Normalized Vth vs. TJ**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7** Switching Time Waveform

**Fig.8** EAS Waveform

## SOT223 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.800	1.520	0.071	0.060
A1	0.100	0.000	0.004	0.000
A2	1.700	1.500	0.067	0.059
b	0.820	0.660	0.032	0.026
c	0.350	0.250	0.014	0.010
D	6.400	6.200	0.252	0.244
D1	3.100	2.900	0.122	0.114
E	3.700	3.300	0.146	0.130
E1	7.070	6.830	0.278	0.269
e	2.30(BSC)		0.091(BSC)	
e1	4.700	4.500	0.185	0.177
L	1.150	0.900	0.045	0.035
θ	10°	0°	10°	0°

## SOT223 RECOMMENDED LAND PATTERN

